

IN THE CLAIMS:

1-7 (Cancelled).

8. (New) A method for manufacturing an optoelectronic semiconductor chip component comprising a two-pole surface mount technology (SMT) miniature housing in lead frame technique for an optoelectronic semiconductor chip, comprising the steps of:

 punching out first and second lead frame parts each having a portion for extending into the housing and a leg portion for serving as a respective solder terminal running at a right angle to the portion extending into the housing;

 pre-housing the lead frame parts with said miniature housing such that said right-angle leg portions of the lead frame parts forming solder terminals are positioned at two opposite sides of the housing and extend to and terminate at a bottom of the housing serving as a mounting surface for mounting the housing onto at least one of a printed circuit board and another mother board with the mounting surface on a top of the at least one of printed circuit board and mother board and ends of the solder terminals terminating at the top surface of the at least one of printing circuit board and mother board, and such that during the entire method no trimming and shaping the solder terminals is carried out so that no bending stress is exerted on the housing, and wherein said housing having a space recessed therein which serves as a reflector;

 mounting the optoelectronic semiconductor chip inside the space on the first lead frame part and contacting the semiconductor chip to the second lead frame part; and

 casting out the semiconductor chip in the space with a casting resin.

9. (New) The method according to claim 8 wherein the solder terminals have a thickness of approximately 0.2 mm – 0.5 mm.

10. (New) The method according to claim 8 wherein the optoelectronic chip component has side-looking emission characteristics.

11. (New) The method according to claim 8 wherein the optoelectronic chip component has side-looking reception characteristics.

12. (New) A method for manufacturing an optoelectronic semiconductor chip component, comprising the steps of:

punching out first and second lead frame parts each having a portion for extending into the housing and a leg portion for serving as a respective solder terminal running at a right angle to the portion extending into the housing;

housing the lead frame parts within a surface mount technology such that said right-angle leg portions of the lead frame parts forming solder terminals are positioned at opposite sides of the housing and extend to and terminate at a bottom of the housing serving as a mounting surface for mounting the housing onto at least one of a printed circuit board and another mother board with the mounting surface on a top of the at least one of printed circuit board and mother board and ends of the solder terminals terminating at the top surface of the at least one of printing circuit board and mother board, and such that no trimming and shaping of the solder terminals is carried out after the housing of the lead frame parts so that no bending stress is exerted on the housing, and wherein said housing having a space recessed therein which serves as a reflector;

mounting the optoelectronic semiconductor chip inside the space on the first lead frame part and contacting the semiconductor chip to the second lead frame part; and

filling the space with a filling material.

13. (New) The method according to claim 8 wherein the filling material comprises a casting resin.